IMAPS Advanced Technology Conference and Tabletop Exhibition on

Non-Hermetic Packaging Technology for Reliable Microelectronics

Rosen Centre Hotel
Orlando, Florida - USA
JANUARY 18, 2012

Final Program

Technical Co-Chairs:

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Corporate Sponsor:

Organized by:
International Microelectronics And Packaging Society (**IMAPS**)
Bringing together the entire microelectronics supply chain!™

IMAPS Welcomes the 2012 Non-Hermetic Packaging Technology for Reliable Microelectronics Exhibitors

as of January 11, 2012

Wednesday, January 18th

Exhibit Hours: 10:00 am - 5:00 pm

AI Technology, Inc.
Endicott Interconnect Technologies, Inc.
Geib Refining Corporation
IC Assembly Services Inc.
Interplex Engineered Products, Inc.
Kyocera America, Inc.
Mastermelt America
Multisorb Technologies
NAMICS Corporation
Materion Corporation
Quik-Pak
Specialty Coating Systems Inc.
SST International
Tektronix Component Solutions

CORPORATE SPONSOR

Thank you for your support!

Wednesday, January 18, 2011

Registration: 7:00 am - 6:00 pm

Continental Breakfast: 7:00 am - 8:00 am

Exhibit Opens: 10:00 am - 5:00 pm

Opening Remarks: 8:00 am - 8:15 am

Technical Co-Chair: Thomas J. Green
TJ Green Associates LLC

Moisture Failures in Electronic Devices
Robert K. Lowry, Electronic Materials Characterization

Class Y Update
Shri G. Agarwal, Jet Propulsion Laboratory/NASA

Verification of the QSS Model for Predicting Moisture Ingress in Hollow Plastic Packages
Ray Pearson, Lehigh University

Advantages of using LCP Based Pre-Molded Leadframe Packages for RF & MEMS Applications
Andy Longford, Interplex Engineered Products/PandA Europe; Jack Matlis, Interplex Engineered Products USA; Joseph Lynch, Interplex Industries Inc, USA

Coffee Break in Exhibit Hall: 10:15 am - 10:45 am

Development of Epoxy Sealed Packages for MEMS
S. Joshua Jacobs, Texas Instruments Inc.

Near-Hermetic Polymer Based Ultra-Thin Packages for Consumer Electronics and Bio-Electronics
Venky Sundaram, Georgia Institute of Technology (PRC)

Lunch in the Exhibit Hall: 11:45 am - 1:30 pm

KEYNOTE PRESENTATION: 1:30 pm - 2:00 pm
Title: Infusion of New Technology into the QML System
Speaker: Dr. Shri G. Agarwal, Program Manger, Jet Propulsion Laboratory/NASA

Dr. Agarwal is a Program Manager at NASA / Jet Propulsion Laboratory - California Institute of Technology. Additionally, he is the NASA point of contact on all matters related to QML (Qualified Manufacturer's List) microcircuits. He has over 35 years experience, and several publications to his credit. He received numerous awards for supporting NASA/JPL space flight projects. He holds Master's degrees from Agra University, India; IIT Delhi, India; and USC, Los Angeles. Currently, Shri is leading a NASA championed effort for the worldwide space community to bring the complex state-of-the-art non-hermetic microcircuits into the QML system (a.k.a. the Class Y initiative).

Characterization of Plastic Encapsulants for Packaging of Non-Hermetic Electronic Modules for Monitoring of Steam Sterilizers
Jinto George, John Barrett, Cork Institute of Technology

Low Cost, Non-Hermetic Multi-Chip Module
Matthew Gruber, Lockheed Martin

Coffee Break in Exhibit Hall: 3:00 pm - 3:30 pm

Corporate Sponsor Presentation: 3:00 pm - 3:10 pm

➔ ***Over***

Wafer-Level Parylene Diffusion Barriers for a Self-Referenced CMOS LC Oscillator
Nathaniel Gaskin, Bhusan Gupta, Integrated Device Technology

Advanced Conformal Barrier Technology for Non-Hermetic Packaging of Electronics
Rakesh Kumar, Specialty Coating Systems, Inc.

Moisture Sensing in Microelectronic Packages
TJ Green Associates LLC

Open Panel Discussion: 5:00 pm - 6:00 pm
Government - Academia - OEMs - Suppliers

Closing Remark: 6:00 pm
Robert Lowry, Electronic Materials Consultant

A Special Thank You

To all the members of the Program Committee,
the Chairs, Speakers, Corporate Sponsor, and Exhibitors.

Your Participation is Greatly Appreciated!

Corporate Sponsor

MATERION

Mark Your Calendar - 2012 Event Dates!

ATW and Tabletop Exhibition on
RF and Microwave Packaging
The Crowne Plaza San Diego
San Diego, California - USA
February 7 - 8, 2012
www.imaps.org/rf

ATW and Symposium with Tabletop Exhibition on
3D and Conformable Printed Electronic Packaging
(Materials, Manufacturing & Applications)
University of Texas
El Paso, Texas - USA
February 22 - 23, 2012
www.imaps.org/printed

Global Business Council (GBC) Spring Conference
Radisson Fort McDowell Resort and Casino
Scottsdale/Fountain Hills, Arizona - USA
March 4 - 5, 2012
www.imaps.org/gbc
Co-located with Device Packaging Conference and Exhibition
(March 5 - 8)

International Conference and Exhibition on Device Packaging
Radisson Fort McDowell Resort and Casino
Scottsdale, Arizona - USA
March 5 - 8, 2012
www.imaps.org/devicepackaging

IMAPS/ACerS 8th International Conference and Exhibition on
Ceramic Interconnect and Ceramic Microsystems
Technologies (CICMT 2012)
Radisson Blu Hotel
Erfurt, Germany
April 16 - 19, 2012
www.cicmt.org

International Conference and Tabletop Exhibition on High
Temperature Electronics (HiTEC 2012)
Albuquerque Marriott Pyramid North
Albuquerque, New Mexico - USA
May 8 - 10, 2012
www.imaps.org/hitec

International Symposium on Microelectronics
(IMAPS 2012)
Town and Country Convention Center
San Diego, California - USA
September 9 - 13, 2012
www.imaps2012.org

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This page is provided for you to take notes during the session.

CD-ROM of presentations (containing the extended abstract and presentation as submitted by the presenter) will be mailed 15 business days after the event.

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